

Amendments to the Specification:

Please replace the paragraph beginning on page 4, line 11, with the following rewritten paragraph:

In a fourth aspect, the metal-coated substrate according to any one of the first to third aspects is provided, wherein ~~more than one kind~~ at least one or more kind of elements selected ~~from~~ from Si, Ti, and Al are contained from a joining interface between the metal layer and the thermoplastic film layer toward the metal layer.

Please replace the paragraph beginning on page 8, line 24, with the following rewritten paragraph:

In a tenth aspect, the manufacturing method of the metal-coated substrate according to the ninth aspect is provided, wherein before the metal layer is formed, an organic substance containing ~~more than one kind~~ at least one or more kind of elements selected from Si, Ti, and Al is deposited on the thermoplastic film layer.

Please replace the paragraph beginning on page 9, line 3, with the following rewritten paragraph:

In an eleventh aspect, the manufacturing method of the metal-coated substrate according to the tenth aspect is provided, comprising the steps of:

allowing the organic substance containing ~~more than one kind~~ at least one or more kind of elements selected from Si, Ti, and Al to be deposited on the thermoplastic film layer before the metal layer is formed; and

heat-treating at 150°C the laminated plastic film having the organic substance containing ~~more than one kind~~ at least one or more kind of elements selected ~~from~~ from the Si, Ti, and Al deposited thereon.

Please replace the paragraph beginning on page 9, line 13, with the following rewritten paragraph:

In a twelfth aspect, the manufacturing method of the metal-coated substrate according to the eleventh aspect is provided, comprising the steps of:

allowing the organic substance containing ~~more than one kind~~ at least one or more kind of elements selected ~~from~~ from Si, Ti, and Al to be deposited on the thermoplastic film layer before the metal layer is formed; and

heat-treating at 150°C the laminated plastic film having the organic substance containing ~~more than one kind~~ at least one or more kind of elements selected from the Si, Ti, and Al deposited thereon,

wherein the above two steps are simultaneously performed.

Please replace the paragraph beginning on page 21, line 13, with the following rewritten paragraph:

By allowing the organic substance such as silane coupling agent, silane compound, or silanol compound to be deposited on the laminated plastic film, as an undercoat layer for improving a heat-resistant adhesiveness as will be describe later, it is possible to eliminate the step of providing a layer containing metal or alloy of ~~more than one kind~~ at least one or more kind of elements selected from Cr, Ni, Mo, W, V, Ti, Si, Fe and Al, for example, as a seed layer. By eliminating the seed layer, it becomes possible to simplify a further etching step in the post process, thereby contributing to an improvement of the productivity, and this is preferable.

Please replace the paragraph beginning on page 22, line 20, with the following rewritten paragraph:

Further, as a structure of not performing a deposition treatment of the organic substance, an undercoat layer may be provided in a part of a lowermost layer contacting the thermoplastic film layer in the aforementioned seed layer. When the structure of providing the undercoat layer in the seed layer is adopted, the layer containing the metal or alloy of

~~more than one kind~~ at least one or more kind of element selected from Cr, Ni, Mo, W, V, Ti, Si, Fe, and Al as an undercoat layer can be selected, for example. When the structure of providing the undercoat layer is adopted, the undercoat layer of Cr and Ni, etc, may be formed on the aforementioned temperature-controlled laminated plastic film by the vapor deposition method, and further the metal layer having the oxidation resistant alloy such as copper or phosphor bronze and brass containing the copper as a main phase may be formed on the undercoat layer.